

## Discription

The XESD2FD3V3E is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.

## Applications

- | Cellular phones audio
- | MP3 players
- | Digital cameras
- | Portable applications
- | mobile telephone

## Features

- | Small Body Outline Dimensions:  
0.039" x 0.024"(1.0 mm x 0.60 mm)
- | Low Body Height: 0.020" (0.50 mm)
- | Stand-off Voltage: 3.3 V – 12 V
- | Low Leakage
- | Response Time is Typically < 1 ns
- | ESD Rating of Class 3 (> 16 kV) per Human Body Model
- | IEC61000-4-2 Level 4 ESD Protection
- | These are Pb-Free Devices
- | We declare that the material of product compliance with RoHS requirements.
- | S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.



SOD882

## Ordering information

Device	Marking	Shipping
XESD2FD3V3E	E	10000/Tape&Reel

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air Contact Contact discharge		±15 ±8	kV kV
ESD Voltage Per Human Body Model		16	kV
Total Power Dissipation on FR-5 Board (Note 1) @ T <sub>A</sub> =25°C	PD	150	mW
Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 to 150	°C
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	°C

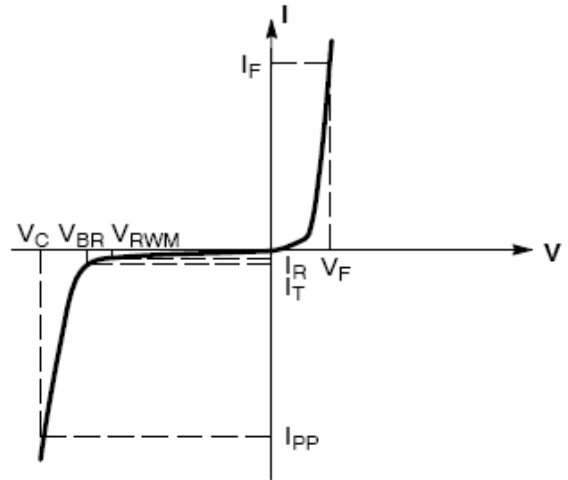
Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0\*0.75\*0.62 in.

## ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$
$P_{pk}$	Peak Power Dissipation
C	Max. Capacitance @ $V_R = 0$ and $f = 1$ MHz



**Uni-Directional TVS**

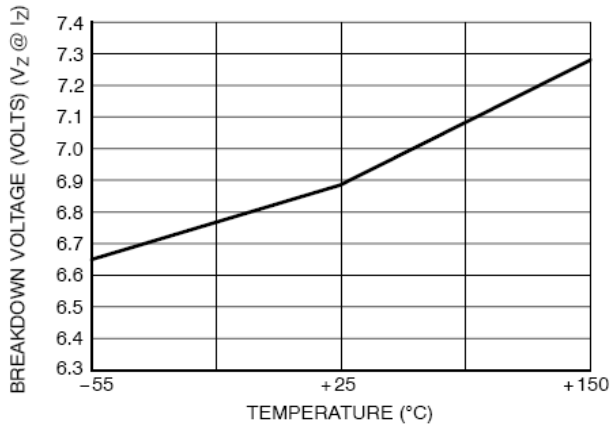
## ELECTRICAL CHARACTERISTICS ( $T_A=25^\circ\text{C}$ unless otherwise noted, $V_F=0.9\text{V}$ Max. @ $I_F=10\text{Ma}$ for all types)

Device	$V_{RWM}$ (V)	$I_R$ ( $\mu\text{A}$ ) @ $V_{RWM}$	$V_{BR}$ (V) @ $I_T$ (Note 2)	$I_T$ (mA)	$I_{PP}$ (A) (Note 3)	$V_C$ (V) @ Max $I_{PP}$ (Note 3)	$P_{PK}$ (W) (8*20 $\mu\text{s}$ )	C (pF)
	Max	Max	Min		Max	Max	Typ	Typ
XESD2FD3V3E	3.3	2.5	5.0	1.0	9.8	10.4	102	80

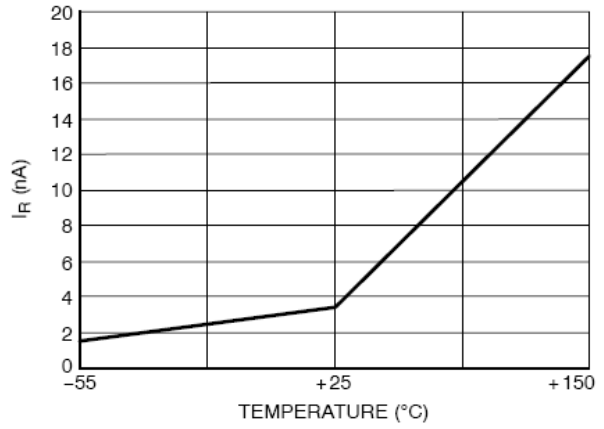
Other voltage available upon request.

- $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of  $25^\circ\text{C}$
- Surge current waveform per Figure 3.

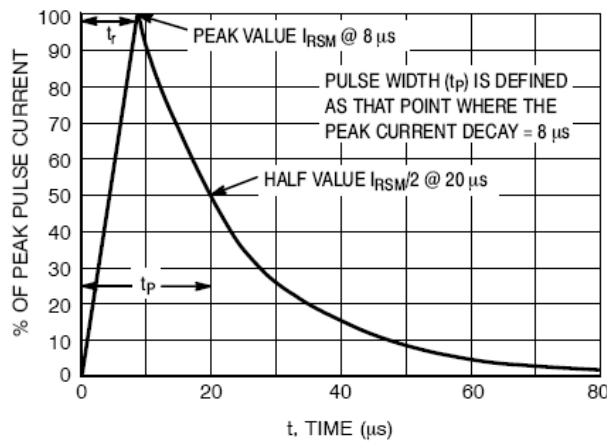
TYPICAL CHARACTERISTICS



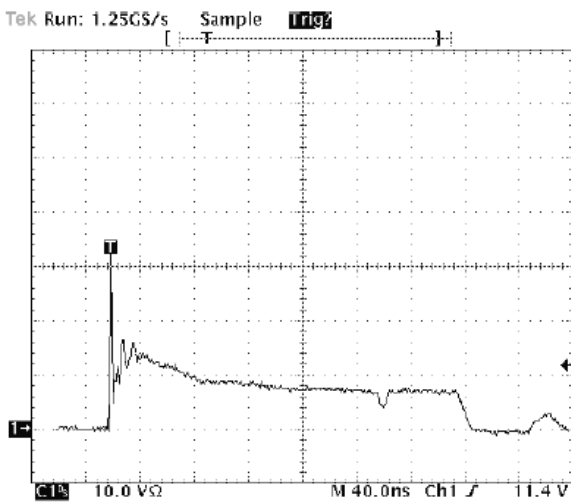
**Figure 1. Typical Breakdown Voltage versus Temperature**



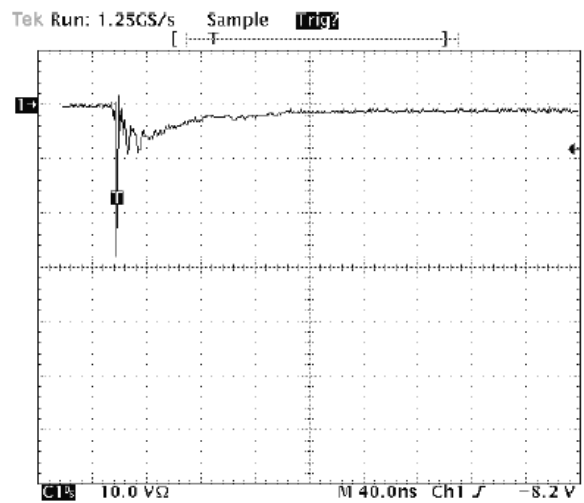
**Fig 2. Typical Leakage Current versus Temperature**



**Figure 3. 8\*20  $\mu s$  Pulse Waveform**



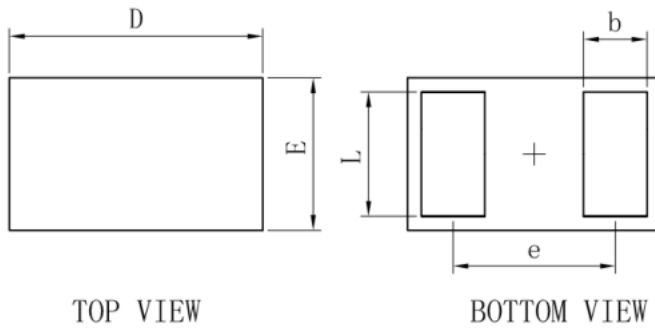
**Figure 4. Positive 8kV contact per IEC 61000-4-2-**



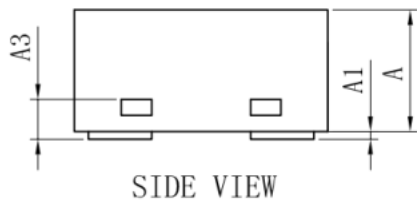
**Fig 5. Negative 8kV contact per IEC 61000-4-2-**

**OUTLINE AND DIMENSIONS**

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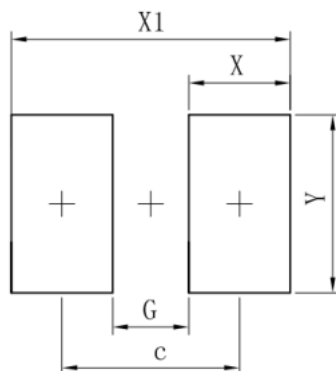


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Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	-	0.64	-
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	-	0.05
A3	0.127REF.		
All Dimensions in mm			



**SOLDERING FOOTPRINT**

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Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70